

**In the Claims**

Cancel claims 11-25, without prejudice.

1        1.        (Previously amended) A method for removing contaminate particulate matter from  
2 a contaminate particle containing substrate surface comprising the steps of:

3        applying a sacrificial coating of a material to a substrate surface containing undesirable  
4        particulate matter thereon, which material is to encapsulate and suspend the  
5        undesirable particles therein;

6        fluidizing the material if necessary;

7        applying energy to the coated substrate to dislodge at least some of the particulate  
8        matter from the surface of the substrate into the fluid sacrificial coating such that  
9        the particulate matter is partially or fully encapsulated and suspended within the  
10        sacrificial coating forming a particulate matter containing sacrificial material  
11        coating;

12        forming the fluidized particulate matter containing sacrificial material coating into a  
13        strippable film; and

14        removing the particulate matter containing sacrificial material coating strippable film  
15        from the substrate surface providing a substrate surface having less particulate  
16        matter thereon.

1        2.        (original) The method of claim 1 wherein the substrate is a semiconductor wafer.

1        3.        (original) The method of claim 1 wherein the sacrificial coating material is a fluid.

1        4.        (original) The method of claim 1 wherein the energy used is sonic energy.

1        5.        (original) The method of claim 1 wherein the energy used is thermal, centrifugal,  
2        magnetic or vibrational.

1        6.        (original) The method of claim 1 wherein the sacrificial coating material is a  
2        liquid.

1        7.        (original) The method of claim 1 wherein the sacrificial coating material is a  
2        curable polymer.

1        8.-9.    (canceled)

1        10.       (original) The method of claim 1 wherein the material is a gas, liquid, vapor or  
2        fluid polymer.

1        11.-25. (Canceled)

- 1 26. (Previously added) The method of claim 1 wherein the strippable film is formed
- 2 simultaneously with application of the energy to dislodge the particles.